



Product Change Notification / JAON-04FTWF456

Date:

09-Feb-2021

Product Category:

Power MOSFET Drivers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4540 Initial Notice: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Affected CPNs:

[JAON-04FTWF456_Affected_CPN_02092021.pdf](#)

[JAON-04FTWF456_Affected_CPN_02092021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of a new lead frame design for selected products available in 8L SOIC package using 8900NC die attach and palladium coated copper with gold flash (CuPdAu) bond wire material assembled at MMT assembly site.

Pre Change:

Using lead frame without lead lock

Post Change:

Using lead frame with lead lock

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Microchip Technology Thailand (Branch) / MMT	Microchip Technology Thailand (Branch) / MMT
Wire material	CuPdAu	CuPdAu
Die attach material	8900NC	8900NC
Molding compound material	G600V	G600V
Lead frame material	CDA194	CDA194
Lead Frame Lead Lock	No	Yes
	See attached pre and post change comparison	

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve productivity by qualifying new lead frame design.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:March 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2021				March 2021				
Workweek	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date		X							
Qual Report Availability							X		
Final PCN Issue Date							X		

Method to Identify Change: Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:February 9, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-04FTWF456_Qual_Plan.pdf](#)

[PCN_JAON-04FTWF456_Pre and Post Change_Summary.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

TC4426ACOA
TC4426AVOA
TC4426AEOA
TC4426AEOA713
TC4426ACOA713
TC4426AVOA713
TC4427ACOA
TC4427AVOA
TC4427AEOA
TC4427AEOAAAA
TC4427AEOA713
TC4427AEOA713AAA
TC4427ACOA713
TC4427AVOA713
TC4428ACOA
TC4428AVOA
TC4428AEOA
TC4428AEOA713
TC4428ACOA713
TC4428ACOA713-GTD
TC4428AVOA713
TC1426COA
TC426COA
TC4426COA
TC4426VOA
TC426EOA
TC4426EOA
TC426EOA713
TC4426EOA713
TC1426COA713
TC426COA713
TC4426COA713
TC4426COA713CAA
TC4426VOA713
TC1427COA
TC427COA
TC4427COA
TC427VOA
TC4427VOA
TC427EOA
TC4427EOA
TC427EOA713
TC4427EOA713
TC4427COA723
TC1427COA713
TC427COA713

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TC4427COA713

TC4427COA713HAZ

TC427VOA713

TC4427VOA713

TC1428COA

TC428COA

TC4428COA

TC4428DCOA

TC428VOA

TC4428VOA

TC428EOA

TC4428EOA

TC428EOA713

TC4428EOA713

TC4428COA723

TC1428COA713

TC428COA713

TC4428COA713

TC428VOA713

TC4428VOA713